

MECHANICAL CASE OUTLINE

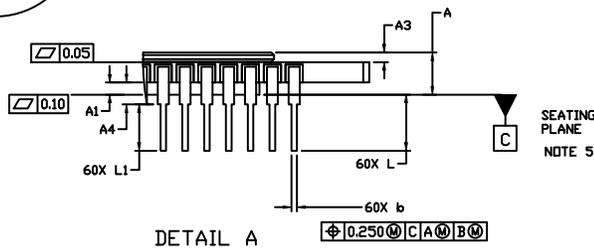
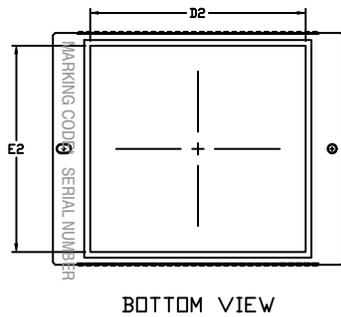
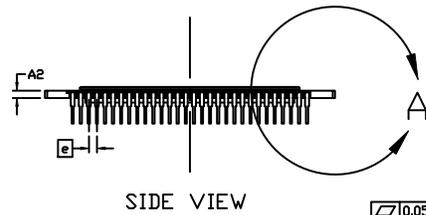
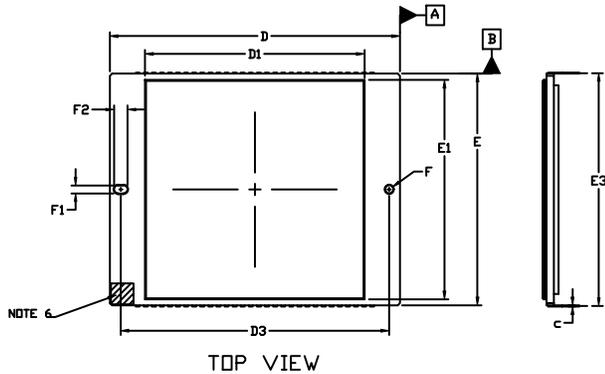
PACKAGE DIMENSIONS

ON Semiconductor®



CERAMIC DIP 60, 63.8x51 CASE 125BR ISSUE O

DATE 06 JUL 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. THE SEATING PLANE IS DEFINED BY THE OUTER HEATSINK SURFACE.
6. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	3.67
A1	0.95	1.05
A2	1.48	1.82
A3	0.80	REF
A4	1.53	2.03
b	0.38	0.54
c	0.20	0.30
D	63.16	64.44
D1	48.18	48.34
D2	47.27	47.53
D3	58.41	59.59
E	50.49	51.51
E1	48.18	48.34
E2	45.27	45.53
E3	50.87	51.63
e	1.778	BSC
F	1.60	1.90
F1	1.60	1.90
F2	2.80	3.10
L	4.32	4.82
L1	3.54	4.04

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